

APPROVED MINUTES

IEEE 802.3 Ethernet Working Group

Working Group Meeting

September 19, 2024

<https://ieee802.org/3/minutes/sep24/index.html>

THURSDAY, 17 SEPTEMBER 2024

Minutes were taken by recording secretary Jon Lewis.

ADMINISTRATIVE MATTERS

Call to order

David Law, Chair of the IEEE 802.3 Ethernet Working Group, called the meeting to order at 19:00 CEST.

Mr. Law asked Adeo Ran and Jon Lewis to stand and recognized them as this year's recipients of the IEEE standards medallion award.

Mr. Law wished a happy birthday to Chad Jones.

Welcome, introductions, and general announcements

Mr. Law noted that it would be too time consuming to have each individual introduce themselves, that introductions would not be done at this hybrid meeting.

Mr. Law showed a list of officers of the IEEE 802.3 Working Group:

IEEE 802.3 Chair: David Law

IEEE 802.3 Vice-Chair: Adam Healey

IEEE 802.3 Secretary: Jon Lewis

IEEE 802.3 Executive Secretary: Chad Jones

IEEE 802.3 Treasurer: Valerie Maguire

IEEE 802.3 Task Force chairs

IEEE P802.3da 10SPE Multidrop Enhancements: Chad Jones

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force: George Zimmerman

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: John D'Ambrosia

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs: Yuanqiu Luo

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet: Jon Lewis

IEEE P802.3.1 (IEEE 802.3.1b) Ethernet MIBs (revision): Marek Hajduczenia

IEEE P802.3.2 (IEEE 802.3.2a) YANG Data Model Definitions (revision) Marek Hajduczenia

IEEE P802.3-2022/Cor 1 (IEEE 802.3dn) Multi-Gigabit Automotive MDI Return Loss: Brett McClellan

IEEE 802.3 Study Group Chair

IEEE 802.3 Single-Pair Ethernet Powering Cabling Restrictions: Chad Jones

IEEE 802.3 Task Force vice-chairs

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: Mark Nowell

Working Group Decorum

Mr. Law introduced the Working Group decorum as described in the opening report. Please see https://iee802.org/3/minutes/sep24/0924_802_3_interim.pdf#page=3.

Mr. Law noted that there should be no recording without permission and that recording was disabled for this meeting in the teleconference tool.

Mr. Law asked if anyone was attending from the press including those who would run a public blog on this meeting other than those limited to summarizing the meeting. There was no response.

Mr. Law introduced the procedure for participants to include their affiliation in their screen name and noted other zoom guidelines for in-person and remote participants including the operation of the queues. Please see

https://iee802.org/3/minutes/sep24/0924_802_3_interim.pdf#page=6.

Review and approval of agenda

Mr. Law noted that a soft copy of the draft agenda had been posted to the minutes section for this meeting.

Mr. Law asked if there were any additions or corrections to the draft agenda.

MOTION #1

Approve the agenda with a change for the approval for 802.3.1b to be conditional.

M: John D’Ambrosia

S: Kent Lusted

Procedural (> 50%)

Motion Passed by unanimous consent, 19:11 CEST

Call for patents

Please see

https://iee802.org/3/minutes/sep24/0924_802_3_interim.pdf#page=11

Mr. Law showed the IEEE patent policy slides.

Mr. Law asked if anyone was aware of any patent claims potentially essential to the proposed standards under development by the IEEE 802.3 Working Group. There was no response.

Mr. Law asked that Mr. Lewis record that:

The patent policy, per the latest PatCom slide set, was shown

There was no response to the call for potentially essential patent claims

Anyone wishing to submit a letter of assurance can do so at any time by contacting Mr. Law or the PatCom administrator

Mr. Law reminded the group of inappropriate topics that should not be discussed. These included territory, market share, price, ongoing litigation, threatened litigation, etc.

Mr. Law reviewed the IEEE SA copyright slides.

https://iee802.org/3/minutes/sep24/0924_802_3_interim.pdf#page=15 Mr. Law advised participants that:

- IEEE SA's copyright policy is described in Clause 7 of the IEEE SA Standards Board Bylaws and Clause 6.1 of the IEEE SA Standards Board Operations Manual;
- Prior to presentation or submission, you shall notify the Working Group Chair of previously Published material and should assist the Chair in obtaining copyright permission acceptable to IEEE SA. For material that is not previously Published, IEEE is automatically granted a license to use any material that is presented or submitted.

Mr. Law reviewed the IEEE SA participation slides.

https://iee802.org/3/minutes/sep24/0924_802_3_interim.pdf#page=18

Mr. Law advised participants that:

- Participants in the IEEE-SA "individual process" under which the project operates shall act independently of others, including employers, and shall act based on their qualifications and experience. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.

General Working Group business

Mr. Law explained the membership requirements (gaining and retaining):

- 75% attendance at 2 of last 4 plenary meetings (a qualifying interim may be substituted for one plenary)
- Request to become member during IEEE 802.3 potential voter agenda item
- Participate in 2 of last 3 WG ballots to retain membership
- Maintain valid contact information
- Consistent declaration of affiliation

LIAISONS

External Liaison letters (old)

ITU-T SG15: Revision of Recommendation G.652 [liaison letter](#) and attachment [1](#) and [2](#)

ITU-T SG15: B400G work and EVM [liaison letter](#) and [attachment](#)

ITU-T SG15: Access Network Transport (ANT) and Home Network Transport (HNT) Standards Overviews and Work Plans [liaison letter](#)

ITU-T SG15: Access Network Transport (ANT) Standards Overview and Work Plan [liaison letter](#)

ITU-T SG15: Home Network Transport (HNT) Standards Overview and Work Plan [liaison letter](#)

ITU-T SG15: OTNT Standardization Work Plan Issue 34 [liaison letter](#) and [attachment](#)

TIA TR-42: Liaison to IEEE 802.3 and review of TIA-TSB-6000 [liaison letter](#)

No formal response. Liaison officer from IEEE 802.3 inform the TIA that no further comments are forthcoming.

Mr. Law stopped the meeting and asked that the IMAT Session Code be provided and paused for participants to log their attendance. Mr. Law resumed the meeting once completed.

Actions:

Future Meetings Report – Chad Jones

https://iee802.org/3/minutes/sep24/0924_meetings.pdf

Straw Poll #1

Considering the opening times for the restaurants in Madrid, Spain, I prefer the adjust the planned times for meetings:

Option 1: 42

Option 2: 36

Abstain: 15

Mr. Jones and Mr. Law thanked the host of the interim meeting, Open Alliance, and the meeting planners.

MOTION #2

Move that IEEE 802.3 accept the Ethernet Alliance offer for the May 2025 interim as detailed in

https://www.ieee802.org/3/minutes/sep24/IEEE802d3_2025MayProposal.pdf

- M: Chad Jones
- S: John D'Ambrosia

By Rule ($\geq 75\%$)

Motion Passed by unanimous consent, 19:39 CEST

Offer to host from July

MOTION #3

Move that IEEE 802.3 accept the Siemens offer for the September 2025 interim as detailed in

- <https://www.ieee802.org/3/minutes/jul24/IEEE%20802.3%20Siemens%20September%202025%20Interim%20Proposal.pdf>

- M: Chad Jones
- S: James Withey

By Rule ($\geq 75\%$)

Motion Withdrawn

Straw Poll #3

I would attend the September 2025 interim per the Siemens offer to host in Cairo, Egypt?

Yes: 21

No: 41

Abstain: 15

Mr. Jones requested to withdraw Motion #3. Mr. Law asked the group if there was any objection, none responded.

Straw Poll #4

I would attend a September 2025 interim in person in:

Sacramento, CA, USA: 45

Boise, ID, USA: 45

Minneapolis, MN, USA: 57

Chicago Rules

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force – John D’Ambrosia

MOTION #4

Move to approve:

- IEEE_802d3_to_ITU_3dj_2409_Q6_Redacted.pdf
- IEEE_802d3_to_ITU_3dj_2409_Q11_Redacted.pdf
- IEEE_802d3_to_ITU_3dj_2409_SG15_Redacted.pdf
- IEEE_802d3_to_OIF_3dj_2409_Redacted.pdf

With editorial license granted to the chair or his appointed agent.

- M: John D’Ambrosia
- S: Kent Lusted

Technical ($\geq 75\%$)

Y: 56 N: 0 A: 4

Motion Passed, 20:32 CEST

IEEE P802.3.1 (IEEE 802.3.1b) SMIV2 Data Models (Revision) Task Force – Marek Hajduczenia

https://ieee802.org/3/minutes/sep24/802d3_task_force_802.3.1_802.3.2_closing.pdf

MOTION #5

- Move to request conditional approval to progress the IEEE P802.3.1b draft to RevCom once the Standards Association ballot process has been successfully completed.
- M: Marek Hajduczenia
- S: John D'Ambrosia

Technical ($\geq 75\%$)

Y: 51 N: 0 A: 8

Motion Passed, 20:40 CEST

IEEE 802.3 Power Delivery Coordinating Committee Ad Hoc – Chad Jones

https://ieee802.org/3/minutes/sep24/PDCC_adhoc_close_report_0924.pdf

MOTION #6

- Move that the IEEE 802.3 Working Group approve:
IEEE_802d3_to_IEC_TC64_0924_1_draft_D3p0.doc and
IEEE_802d3_to_IEC_TC64_0924_2_draft_D1p0.doc with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to ISO/IEC TC64 and the “Directions to IEEE 802.3 liaison officer to IEC TC 64/MT 2” shown on slide 5 of this presentation
- M: Chad Jones
- S: George Zimmerman

Technical ($\geq 75\%$)

Motion Passed by unanimous consent, 20:51 CEST

Mr. Lewis announced to the group that two new consensus building activities would be starting and that information would be sent to the reflector and meeting coordinates would be on the IEEE 802.3 Call and Meeting calendar.

Channel Operating Margin (COM) Code as Open Source - Kent Lusted

https://ieee802.org/3/minutes/sep24/IEEE_802p3_WG_COM_update1.pdf

Mr. Law asked if there was other business for the Working Group.

Mr. Law noted that the agenda had been exhausted and then adjourned the meeting.

Adjourned.

Appendix A: Attendance list for Working Group meeting from IMAT

Name	Employer	Affiliation	IMAT	Zoom
Arroyo, Hector		Analog Devices Inc.	X	X
Beauregard, Francois	Belden Canada ULC	Belden	X	X
Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	X	X
Benyamin, Saied	Ethernovia	Ethernovia	X	X
Borda, jamila josip	BMW Group	in-tech GmbH	X	X
Brown, Matthew	Alphawave	Alphawave	X	X
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.	X	X
Chen, Chan	Self Employed	Independent/AOI	X	X
Cox, Ian		Broadcom Corporation	X	X
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Affiliate of Huawei	X	X
Dawe, Piers J G	NVIDIA	Nvidia	X	X
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.	X	X
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz	X	X
Dudek, Michael	Marvell	Marvell	X	X
Effenberger, Frank	Futurewei Technologies	Futurewei Technologies	X	X
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc	X	X
Fuller, Paul		Marvell	X	X
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.	X	X
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.	X	X
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.	X	X
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation	X	X
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE	X	X
Hajduczenia, Marek	Charter Communications	Charter Communications	X	X
Haydt, Mary Sue	Microchip Technology, Inc.	Microchip Technology, Inc.	X	X
Healey, Adam	Broadcom	Broadcom	X	X
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor	X	X
Ho, Matthew		TE Connectivity	X	X
Hoshino, Masayuki		Continental Automotive	X	X
Huber, Thomas	Nokia	Nokia	X	X
Huebner, Bernd	Cisco Systems, Inc.	Cisco Systems	X	
Huszak, Gergely	Self	KONE	X	X
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.	X	X
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD	X	X
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X
Kapoor, Samay	Aviva Links	Aviva Links Inc.	X	X
Kikuta, Tomohiro	Orbray Co., Ltd.	Orbray Co., Ltd.	X	X
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.	X	X

Kimber, Eric	Semtech Ltd	Semtech Ltd	X	X
Klingensmith, William	U.S. Federal Government	U.S. Federal Government	X	X
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X
Kock, Joerg	NXP Semiconductors	NXP Semiconductors	X	X
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation	X	X
Lackner, Hans	QoSCom GmbH	QoSCom GmbH	X	X
Lambert, Angela	Corning Incorporated	Corning Incorporated	X	X
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc	X	X
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise	X	X
Levin, Itamar		Intel Corporation	X	
Lewis, Jon	Dell Technologies	Dell Technologies	X	X
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.	X	X
Lou, Wei		Broadcom Corporation	X	X
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies	X	X
Lusted, Kent	Intel	Intel	X	X
Maguire, Valerie	Copperopolis	Copperopolis, affiliated with CME Consulting and Cisco	X	X
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.	X	X
Maniloff, Eric	Ciena Corporation	Ciena Corporation	X	X
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.	X	X
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.	X	X
Moorwood, Charles	Keysight Technologies	Keysight Technologies	X	X
Muhigana, Ernest		Lumentum	X	X
Muller, Shimon	Enfabrica Corp.	Enfabrica	X	X
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.	X	X
Ng, Hiok Tiaq	Aviva Links Inc.	Aviva Links Inc.	X	X
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)	X	X
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation	X	X
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.	X	X
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.	X	X
Palkert, Thomas	Macom, Samtec	Samtec-Macom	X	X
Pardo, Carlos	Knowledge Development for POF SL	KDPOF	X	X
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.	X	X
Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson	X	X
Parsons, Earl	CommScope, Inc.	CommScope, Inc.	X	X
Paul, Michael	Analog Devices Inc.	Analog Devices	X	X
Pepper, Gerald	Keysight Technologies	Keysight Technologies	X	X
Pineda, Luis	LP Tech Advisors, LLC	LP Tech Advisors, LLC (Samsung; 7Rays; Ethernovia)	X	X
Rabinovich, Rick	Keysight Technologies	Keysight Technologies	X	X

Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X
Royer, Tyler		Senko Advanced Components	X	X
Sakai, Toshiaki	Socionext Inc.	socionext	X	X
Schreiner, Stephan	Rosenberger Hochfrequenztechnik GmbH & Co. KG	Rosenberger	X	X
SERIZAWA, NAOSHI	Yazaki Corporation	Yazaki Corporation	X	X
Shah, Anup	Siemens Corporation	Siemens EDA	X	X
Shakiba, Mohammad	Huawei Technologies Canada	Huawei Technologies Canada; Huawei Technologies Co., Ltd	X	X
Shanbhag, Megha	Tyco	TE Connectivity	X	X
Sharma, Rohit		Molex Incorporated	X	X
Sheffi, Nir	Alphawave	Alphawave	X	X
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	X	X
sisk, jason	University of New Hampshire InterOperability Laboratory (UNH-IOL)	University of New Hampshire InterOperability Laboratory (UNH-IOL)	X	X
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDRIES	X	X
Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Infinera	X	X
Tartaglia, Antonio	Ericsson AB	Ericsson AB	X	X
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT	X	X
Torres, Luisma	Knowledge Development for Plastic Optical Fiber	Knowledge Development for Plastic Optical Fiber	X	X
Tracy, Nathan	TE Connectivity	TE Connectivity	X	X
Tran, Viet	Keysight Technologies	Keysight Technologies	X	X
Tu, Mike	Broadcom Corporation	Broadcom Corporation	X	X
Turner, Max	Ethernovia	Ethernovia	X	X
Ulrichs, Ed	Intel	Intel	X	X
Watanabe, Yuji	AGC Inc.	AGC	X	X
Wienckowski, Natalie	IVN Solutions LLC	IVN Solutions LLC; Ethernovia	X	X
Wingrove, Michael	Ciena Corporation	Ciena Corporation	X	X
Withey, James	Fluke Corporation	Fluke Corporation	X	X
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	
Zerna, Conrad	Aviva Links Inc	Aviva Links Inc	X	X
Zimmerman, George	CME Consulting, Inc.	CME Consulting/ADI, APL Group, Cisco, Marvell, OnSemi, SenTekSe LLC, Sony	X	X

Appendix B: Attendees on Zoom but not on IMAT

Name	Employer	Affiliation	Zoom
Andras de Koos		Microchip	X
David Piehler	Dell Technologies	Dell Technologies	X
Yong Son		Optomind	X
Yuch Tian		CMCC	X
Jodi Haasz		IEEE SA	X
Brett McClellan		Marvell	X
Thomas Mueller		Rosenberger	X
Phil Sun		Credo	X
Keyi Zhu		Huawei	X
Tom Williams		Cisco	X
Hao Ren		Huawei	X